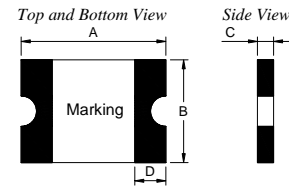


### 1、Physical Dimensions(size of 1812)

Unit:mm

Part Number	A		B		C		D	Marking
	Min	Max	Min	Max	Min	Max	Min	
MSMD050/30	4.37	4.73	3.07	3.41	0.60	1.00	0.30	T050



### 2、Electrical Characteristics

Part Number	I <sub>H</sub> (A)	I <sub>T</sub> (A)	V <sub>max</sub> (V)	I <sub>max</sub> (A)	T <sub>trip</sub> (Max time to trip)		Pd <sub>typ</sub> (W)	R <sub>min</sub> (Ω)	R1 <sub>max</sub> (Ω)
					Current(A)	Time(S)			
MSMD050/30	0.50	1.00	30	40	8.0	0.15	0.8	0.15	1.00

I<sub>H</sub>: Holding Current: maximum current at which the device will not trip in 25°C still air.

I<sub>T</sub>: Tripping Current minimum current at which the device will trip in 25°C still air.

V<sub>max</sub>: Maximum voltage device can withstand without damage at rated current.

I<sub>max</sub>: Maximum fault current device can withstand without damage at rated voltage.

T<sub>trip</sub>: Maximum time to trip(s) at assigned current.

Pd<sub>typ</sub>: Rated working power.

R<sub>min</sub>: Minimum resistance of device prior to trip at 25°C.

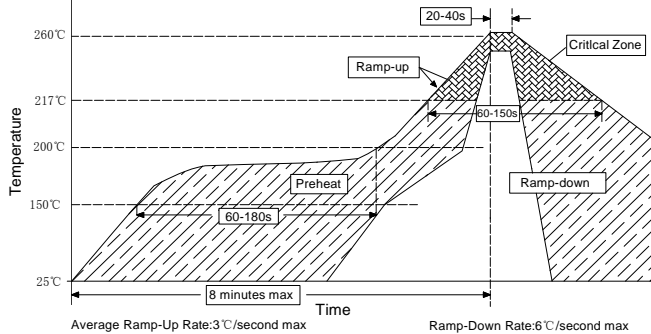
R1<sub>max</sub>: Maximum resistance of device is measured one hours post reflow at 25°C.

Noted: All electrical function test is conducted after PCB mounted.

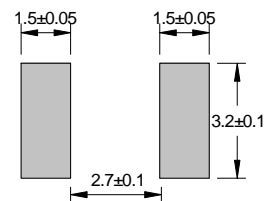
### 3、Thermal Derating

MSMD050/30	Maximum ambient operating temperature								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
Hold Current(A)	0.77	0.68	0.59	0.50	0.44	0.40	0.37	0.33	0.29
Trip Current(A)	1.54	1.36	1.18	1.00	0.88	0.80	0.74	0.66	0.58

### 4、Solder Reflow Recommendations



Recommended Pad Layout(mm)



Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

### 5、Package Information

Packing quantity: 2000PCS/Reel

Note: Reel packaging per EIA-481-1 standard